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Understanding Embedded - Microprocessors

Embedded microprocessors are specialized computing chips designed to perform specific tasks within an embedded system. Unlike general-purpose microprocessors found in personal computers, embedded microprocessors are tailored for dedicated functions within larger systems, offering optimized performance, efficiency, and reliability. These microprocessors are integral to the operation of countless electronic devices, providing the computational power necessary for controlling processes, handling data, and managing communications.

Applications of Embedded - Microprocessors

Embedded microprocessors are utilized across a broad spectrum of applications, making them indispensable in

Details	
Product Status	Obsolete
Core Processor	MPC8xx
Number of Cores/Bus Width	1 Core, 32-Bit
Speed	100MHz
Co-Processors/DSP	Communications; CPM
RAM Controllers	DRAM
Graphics Acceleration	No
Display & Interface Controllers	-
Ethernet	10Mbps (4), 10/100Mbps (1)
SATA	-
USB	-
Voltage - I/O	3.3V
Operating Temperature	-40°C ~ 100°C (TA)
Security Features	-
Package / Case	357-BBGA
Supplier Device Package	357-PBGA (25x25)
Purchase URL	https://www.e-xfl.com/product-detail/nxp-semiconductors/mpc866tcvr100a

4 Thermal Characteristics

Table 4 shows the thermal characteristics for the MPC866/859.

Table 4. MPC866/859 Thermal Resistance Data

Rating	Environment		Symbol	Value	Unit
Junction-to-ambient [1]	Natural Convection	Single-layer board (1s)	$R_{\theta JA}$ [2]	37	°C/W
		Four-layer board (2s2p)	$R_{\theta JMA}$ [3]	23	
	Airflow (200 ft/min)	Single-layer board (1s)	$R_{\theta JMA}$ [3]	30	
		Four-layer board (2s2p)	$R_{\theta JMA}$ [3]	19	
Junction-to-board [4]			$R_{\theta JB}$	13	
Junction-to-case [5]			$R_{\theta JC}$	6	
Junction-to-package top [6]	Natural Convection		Ψ_{JT}	2	
	Airflow (200 ft/min)		Ψ_{JT}	2	

1 Junction temperature is a function of on-chip power dissipation, package thermal resistance, mounting site (board) temperature, ambient temperature, airflow, power dissipation of other components on the board, and board thermal resistance.

2 Per SEMI G38-87 and JEDEC JESD51-2 with the single-layer board horizontal.

3 Per JEDEC JESD51-6 with the board horizontal.

4 Thermal resistance between the die and the printed-circuit board per JEDEC JESD51-8. Board temperature is measured on the top surface of the board near the package.

5 Indicates the average thermal resistance between the die and the case top surface as measured by the cold plate method (MIL SPEC-883 Method 1012.1) with the cold plate temperature used for the case temperature. For exposed pad packages where the pad would be expected to be soldered, junction-to-case thermal resistance is a simulated value from the junction to the exposed pad without contact resistance.

6 Thermal characterization parameter indicating the temperature difference between package top and junction temperature per JEDEC JESD51-2.

5 Power Dissipation

Table 5 shows power dissipation information. The modes are 1:1, where CPU and bus speeds are equal, and 2:1 mode, where CPU frequency is twice the bus speed.

Table 5. Power Dissipation (P_D)

Die Revision	Bus Mode	CPU Frequency	Typical [1]	Maximum [2]	Unit
0	1:1	50 MHz	110	140	mW
		66 MHz	150	180	mW
	2:1	66 MHz	140	160	mW
		80 MHz	170	200	mW
		100 MHz	210	250	mW
		133 MHz	260	320	mW

1 Typical power dissipation at VDDL and VDDSYN is at 1.8 V. and VDDH is at 3.3 V.

2 Maximum power dissipation at VDDL and VDDSYN is at 1.9 V, and VDDH is at 3.465 V.

NOTE

Values in Table 5 represent VDDL based power dissipation and do not include I/O power dissipation over VDDH. I/O power dissipation varies widely by application due to buffer current, depending on external circuitry. The VDDSYN power dissipation is negligible.

6 DC Characteristics

Table 6 shows the DC electrical characteristics for the MPC866/859.

Table 6. DC Electrical Specifications

Characteristic	Symbol	Min	Max	Unit
Operating voltage	VDDL (core)	1.7	1.9	V
	VDDH (I/O)	3.135	3.465	V
	VDDSYN [1]	1.7	1.9	V
	Difference between VDDL to VDDSYN	—	100	mV
Input high voltage (all inputs except EXTAL and EXTCLK) [2]	VIH	2.0	3.465	V

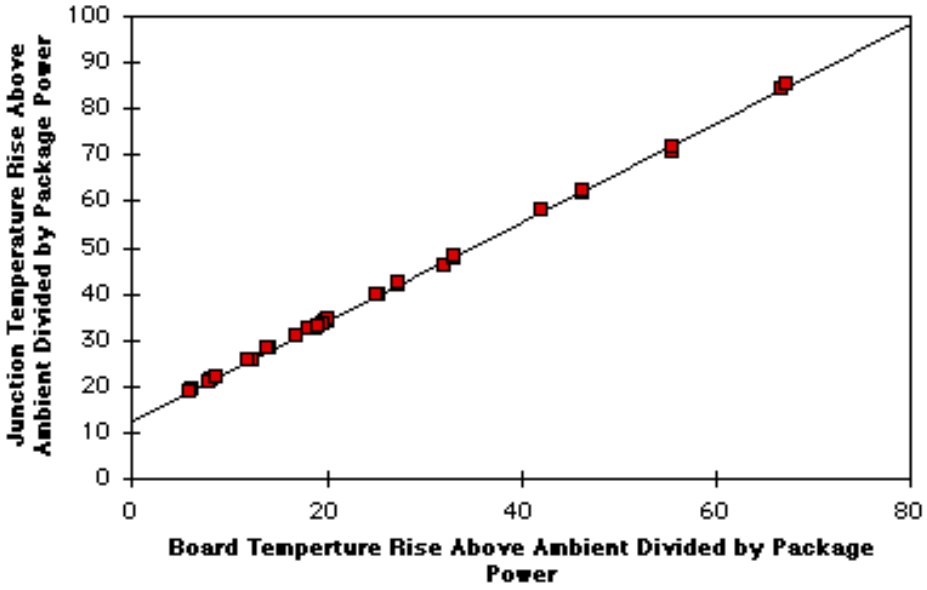

Figure 3. Effect of Board Temperature Rise on Thermal Behavior

If the board temperature is known, an estimate of the junction temperature in the environment can be made using the following equation:

$T_J = T_B + (R_{\theta JB} \times P_D)$

where:

$R_{\theta JB}$ = junction-to-board thermal resistance (ºC/W)

T_B = board temperature ºC

P_D = power dissipation in package

If the board temperature is known and the heat loss from the package case to the air can be ignored, acceptable predictions of junction temperature can be made. For this method to work, the board and board mounting must be similar to the test board used to determine the junction-to-board thermal resistance, namely a 2s2p (board with a power and a ground plane) and vias attaching the thermal balls to the ground plane.

7.4 Estimation Using Simulation

When the board temperature is not known, a thermal simulation of the application is needed. The simple two-resistor model can be used with the thermal simulation of the application [2], or a more accurate and complex model of the package can be used in the thermal simulation.

7.5 Experimental Determination

To determine the junction temperature of the device in the application after prototypes are available, the thermal characterization parameter (Ψ_{JT}) can be used to determine the junction temperature with a measurement of the temperature at the top center of the package case using the following equation:

$$T_J = T_T + (\Psi_{JT} \times P_D)$$

where:

Ψ_{JT} = thermal characterization parameter

T_T = thermocouple temperature on top of package

P_D = power dissipation in package

The thermal characterization parameter is measured per JESD51-2 specification published by JEDEC using a 40 gauge type T thermocouple epoxied to the top center of the package case. The thermocouple should be positioned so that the thermocouple junction rests on the package. A small amount of epoxy is placed over the thermocouple junction and over about 1 mm of wire extending from the junction. The thermocouple wire is placed flat against the package case to avoid measurement errors caused by cooling effects of the thermocouple wire.

7.6 References

Semiconductor Equipment and Materials International(415) 964-5111
805 East Middlefield Rd.
Mountain View, CA 94043

MIL-SPEC and EIA/JESD (JEDEC) specifications800-854-7179 or
(Available from Global Engineering Documents)303-397-7956

JEDEC Specifications http://www.jedec.org

1. C.E. Triplett and B. Joiner, “An Experimental Characterization of a 272 PBGA Within an Automotive Engine Controller Module,” Proceedings of SemiTherm, San Diego, 1998, pp. 47-54.

2. B. Joiner and V. Adams, “Measurement and Simulation of Junction to Board Thermal Resistance and Its Application in Thermal Modeling,” Proceedings of SemiTherm, San Diego, 1999, pp. 212-220.

This recommendation particularly applies to the address and data buses. Maximum PC trace lengths of 6” are recommended. Capacitance calculations should consider all device loads as well as parasitic capacitances due to the PC traces. Attention to proper PCB layout and bypassing becomes especially critical in systems with higher capacitive loads because these loads create higher transient currents in the V_{DD} and GND circuits. Pull up all unused inputs or signals that will be inputs during reset. Special care should be taken to minimize the noise levels on the PLL supply pins. For more information, please refer to Section 14.4.3, Clock Synthesizer Power (VDDSYN, VSSSYN, VSSSYN1), in the *MPC866 User’s Manual*.

10 Bus Signal Timing

The maximum bus speed supported by the MPC866/859 is 66 MHz. Higher-speed parts must be operated in half-speed bus mode (for example, an MPC866/859 used at 100 MHz must be configured for a 50-MHz bus). Table 7 and Table 8 show the frequency ranges for standard part frequencies.

Table 7. Frequency Ranges for Standard Part Frequencies (1:1 Bus Mode)

Part Freq	50 MHz		66 MHz	
	Min	Max	Min	Max
Core	40	50	40	66.67
Bus	40	50	40	66.67

Table 8. Frequency Ranges for Standard Part Frequencies (2:1 Bus Mode)

Part Freq	50 MHz		66 MHz		100 MHz		133 MHz	
	Min	Max	Min	Max	Min	Max	Min	Max
Core	40	50	40	66.67	40	100	40	133.34
Bus	20	25	20	33.33	20	50	20	66.67

Table 9 shows the timings for the MPC866/859 at 33, 40, 50, and 66 MHz bus operation. The timing for the MPC866/859 bus shown in this table assumes a 50-pF load for maximum delays and a 0-pF load for minimum delays. CLKOUT assumes a 100-pF load maximum delay.

Table 9. Bus Operation Timings

Num	Characteristic	33 MHz		40 MHz		50 MHz		66 MHz		Unit
		Min	Max	Min	Max	Min	Max	Min	Max	
B1	Bus Period (CLKOUT) See Table 7	—	—	—	—	—	—	—	—	ns
B1a	EXTCLK to CLKOUT phase skew	– 2	+2	– 2	+2	– 2	+2	– 2	+2	ns
B1b	CLKOUT frequency jitter peak-to-peak	—	1	—	1	—	1	—	1	ns
B1c	Frequency jitter on EXTCLK	—	0.50	—	0.50	—	0.50	—	0.50	%

Figure 10 shows normal case timing for input data. It also applies to normal read accesses under the control of the UPM in the memory controller.

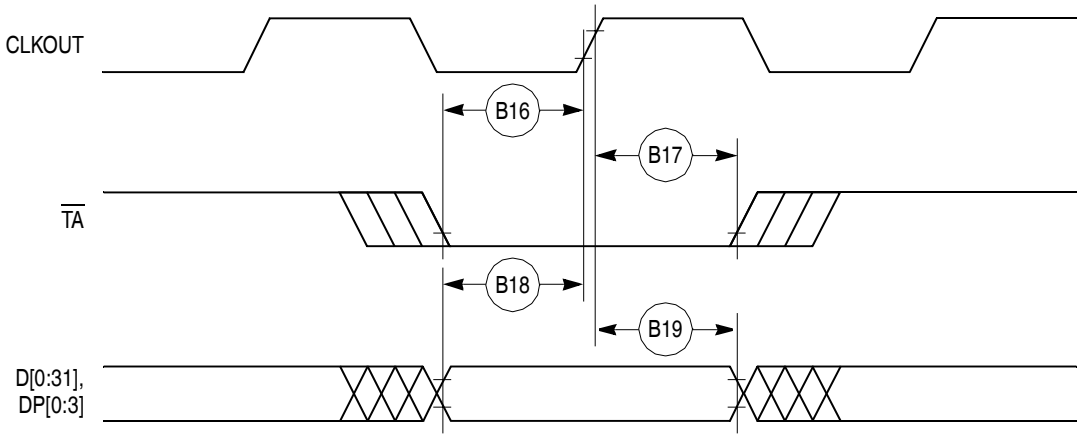

Figure 10. Input Data Timing in Normal Case

Figure 11 shows the timing for the input data controlled by the UPM for data beats where DLT3 = 1 in the UPM RAM words. (This is only the case where data is latched on the falling edge of CLKOUT.)

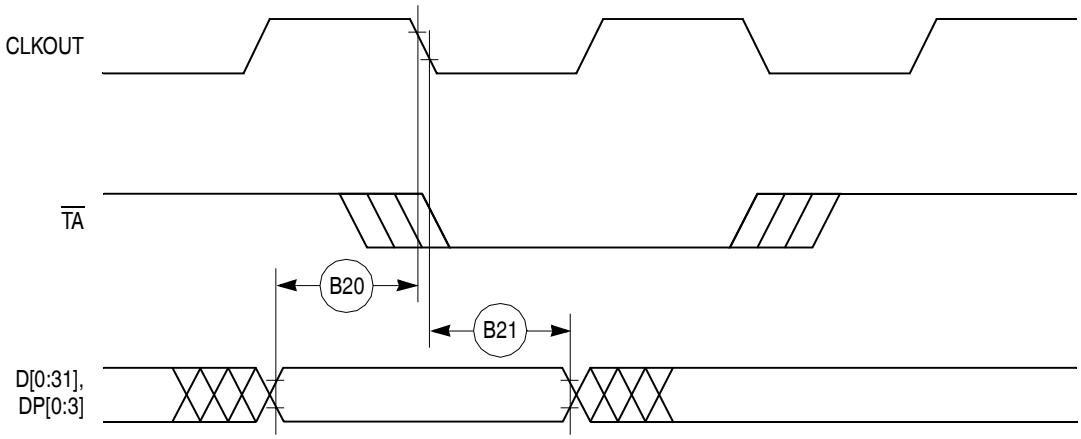

Figure 11. Input Data Timing when Controlled by UPM in the Memory Controller and DLT3 = 1

Figure 16 through Figure 18 show the timing for the external bus write controlled by various GPCM factors.

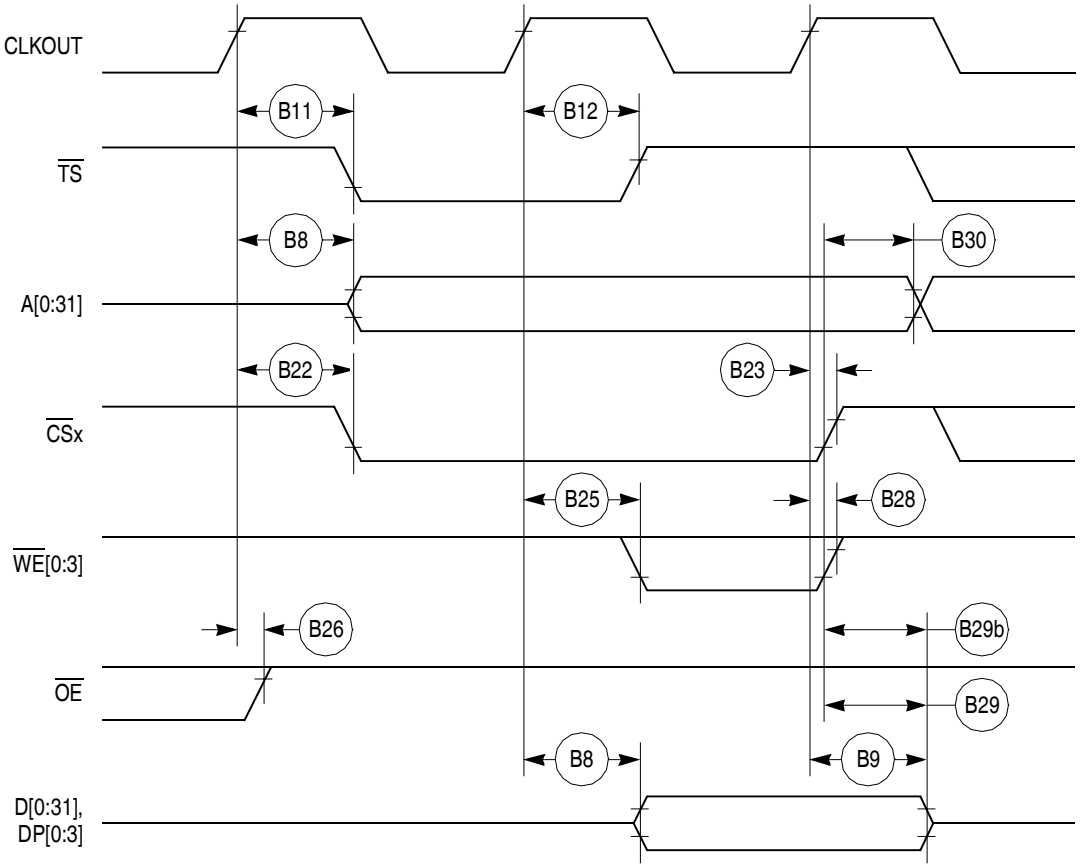

Figure 16. External Bus Write Timing (GPCM Controlled—TRLX = 0 or 1, CSNT = 0)

Figure 23 shows the timing for the asynchronous external master memory access controlled by the GPCM.

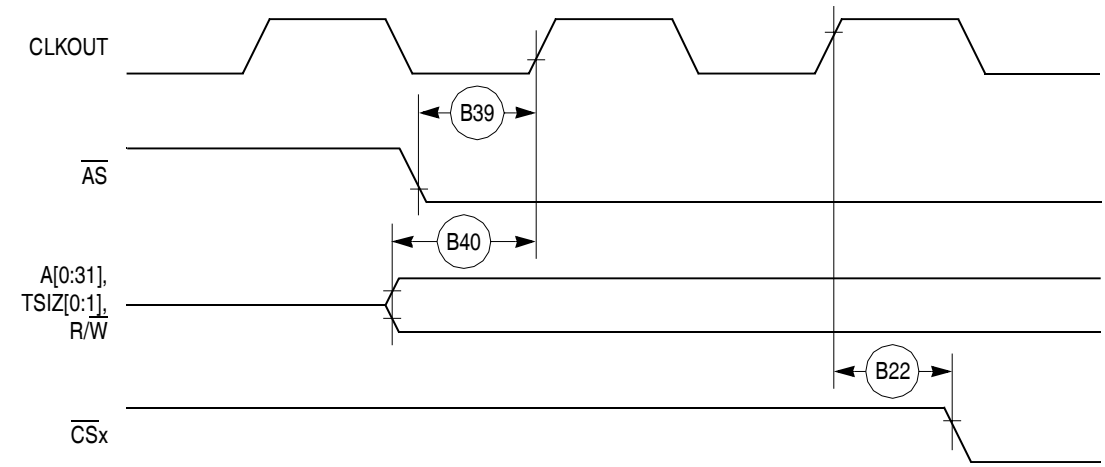

Figure 23. Asynchronous External Master Memory Access Timing (GPCM Controlled—ACS = 00)

Figure 24 shows the timing for the asynchronous external master control signals negation.

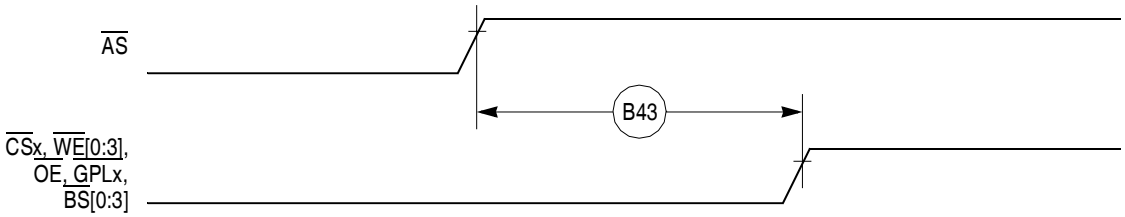

Figure 24. Asynchronous External Master—Control Signals Negation Timing

Table 10 shows the interrupt timing for the MPC866/859.

Table 10. Interrupt Timing

Num	Characteristic [1]	All Frequencies		Unit
		Min	Max	
I39	$\overline{IRQ}$x valid to CLKOUT rising edge (setup time)	6.00	—	ns
I40	$\overline{IRQ}$x hold time after CLKOUT	2.00	—	ns
I41	$\overline{IRQ}$x pulse width low	3.00	—	ns
I42	$\overline{IRQ}$x pulse width high	3.00	—	ns
I43	$\overline{IRQ}$x edge-to-edge time	$4xT_{CLOCKOUT}$	—	—

[1] The timings I39 and I40 describe the testing conditions under which the $\overline{IRQ}$ lines are tested when being defined as level sensitive. The $\overline{IRQ}$ lines are synchronized internally and do not have to be asserted or negated with reference to the CLKOUT.
The timings I41, I42, and I43 are specified to allow the correct function of the $\overline{IRQ}$ lines detection circuitry, and has no direct relation with the total system interrupt latency that the MPC866/859 is able to support.

Table 11. PCMCIA Timing (continued)

Num	Characteristic	33 MHz		40 MHz		50 MHz		66 MHz		Unit
		Min	Max	Min	Max	Min	Max	Min	Max	
P50	CLKOUT to $\overline{\text{PCOE}}$, $\overline{\text{IORD}}$, $\overline{\text{PCWE}}$, $\overline{\text{IOWR}}$ assert time (MAX = 0.00 x B1 + 11.00)	—	11.00	—	11.00	—	11.00	—	11.00	ns
P51	CLKOUT to $\overline{\text{PCOE}}$, $\overline{\text{IORD}}$, $\overline{\text{PCWE}}$, $\overline{\text{IOWR}}$ negate time (MAX = 0.00 x B1 + 11.00)	2.00	11.00	2.00	11.00	2.00	11.00	2.00	11.00	ns
P52	CLKOUT to ALE assert time (MAX = 0.25 x B1 + 6.30)	7.60	13.80	6.30	12.50	5.00	11.30	3.80	10.00	ns
P53	CLKOUT to ALE negate time (MAX = 0.25 x B1 + 8.00)	—	15.60	—	14.30	—	13.00	—	11.80	ns
P54	$\overline{\text{PCWE}}$, $\overline{\text{IOWR}}$ negated to D(0:31) invalid[1] (MIN = 0.25 x B1 – 2.00)	5.60	—	4.30	—	3.00	—	1.80	—	ns
P55	$\overline{\text{WAITA}}$ and $\overline{\text{WAITB}}$ valid to CLKOUT rising edge[1] (MIN = 0.00 x B1 + 8.00)	8.00	—	8.00	—	8.00	—	8.00	—	ns
P56	CLKOUT rising edge to $\overline{\text{WAITA}}$ and $\overline{\text{WAITB}}$ invalid[1] (MIN = 0.00 x B1 + 2.00)	2.00	—	2.00	—	2.00	—	2.00	—	ns

1 PSST = 1. Otherwise, add PSST times cycle time.
PSHT = 0. Otherwise, add PSHT times cycle time.
These synchronous timings define when the $\overline{\text{WAITx}}$ signals are detected in order to freeze (or relieve) the PCMCIA current cycle. The $\overline{\text{WAITx}}$ assertion will be effective only if it is detected 2 cycles before the PSL timer expiration. See PCMCIA Interface in the *MPC866 PowerQUICC User's Manual*.

Figure 27 shows the PCMCIA access cycle timing for the external bus read.

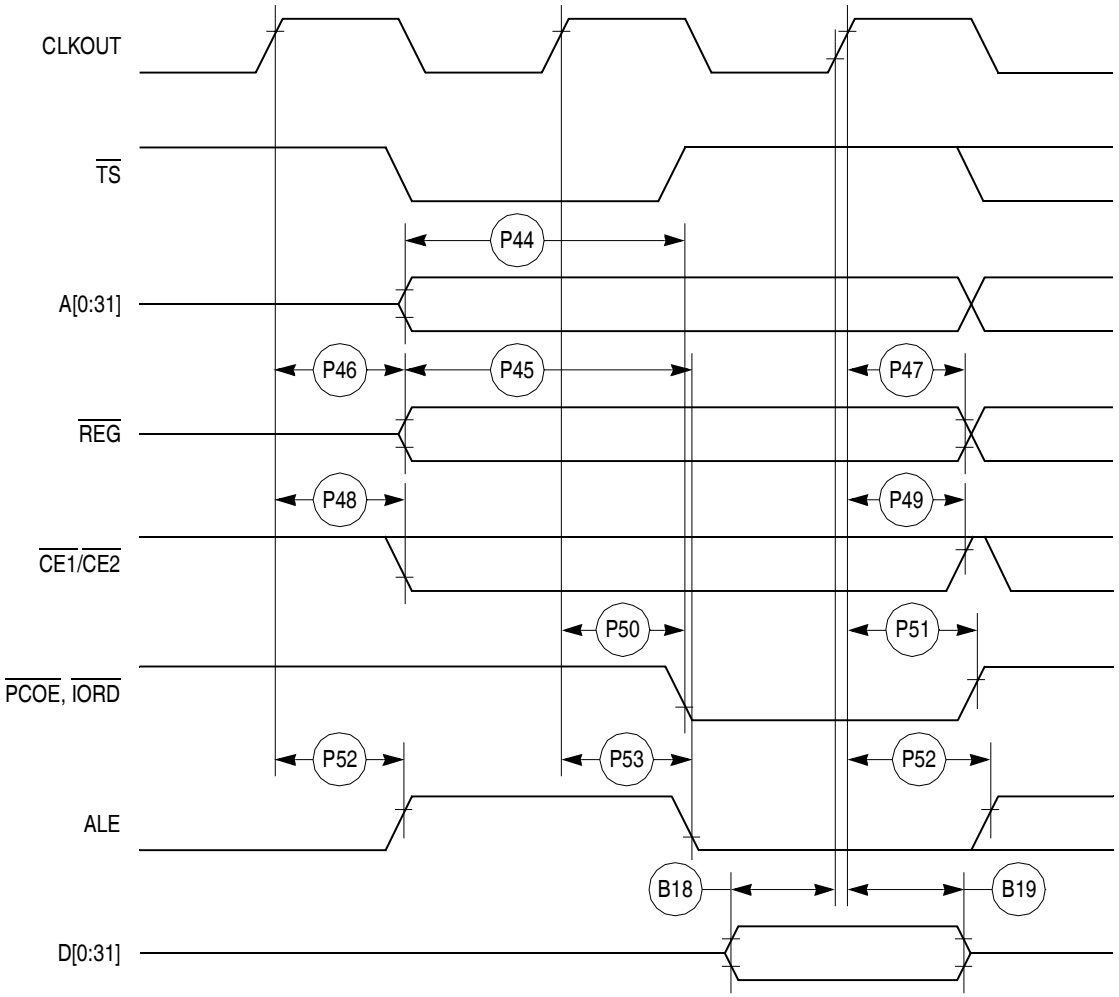

Figure 27. PCMCIA Access Cycles Timing External Bus Read

Figure 28 shows the PCMCIA access cycle timing for the external bus write.

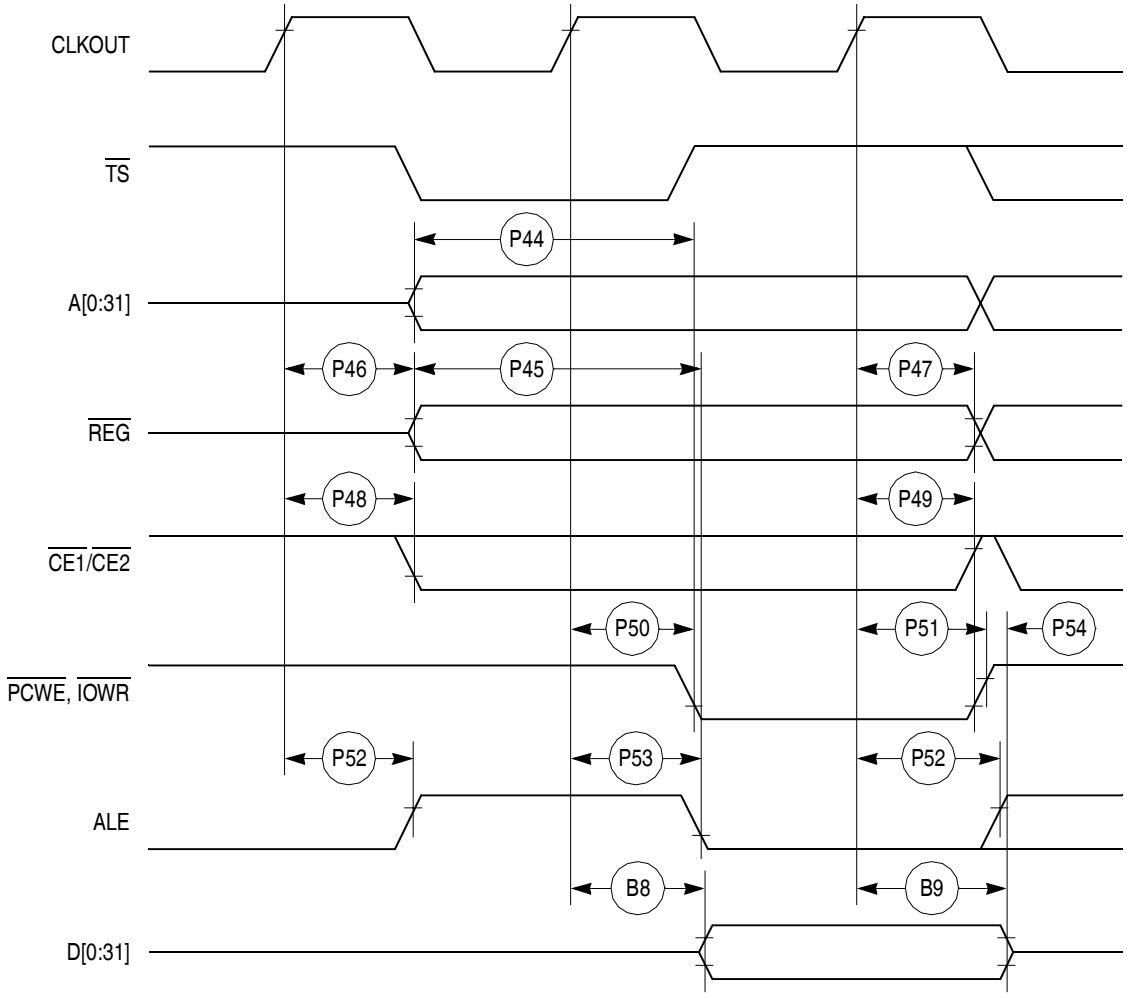

Figure 28. PCMCIA Access Cycles Timing External Bus Write

Figure 29 shows the PCMCIA WAIT signals detection timing.

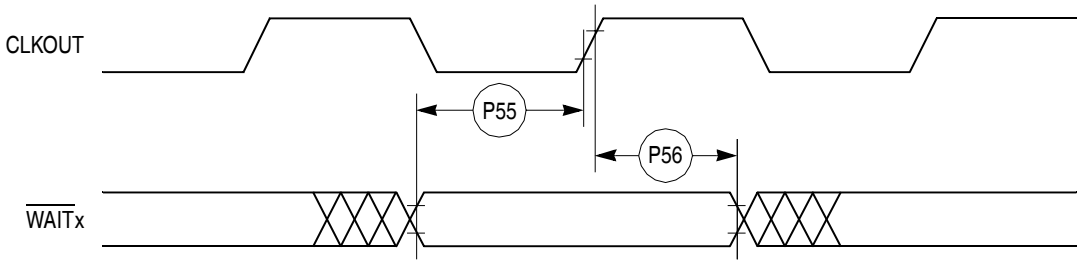

Figure 29. PCMCIA WAIT Signals Detection Timing

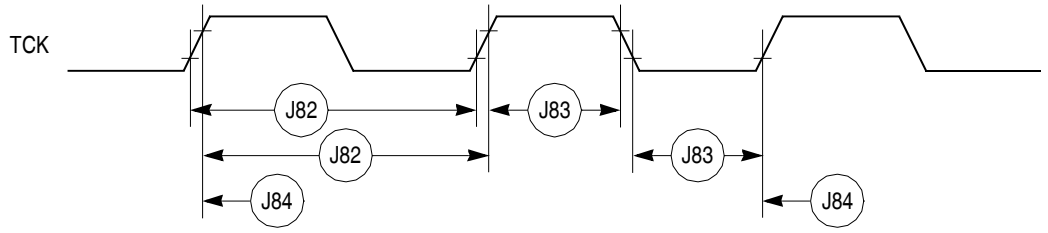

Figure 37. JTAG Test Clock Input Timing

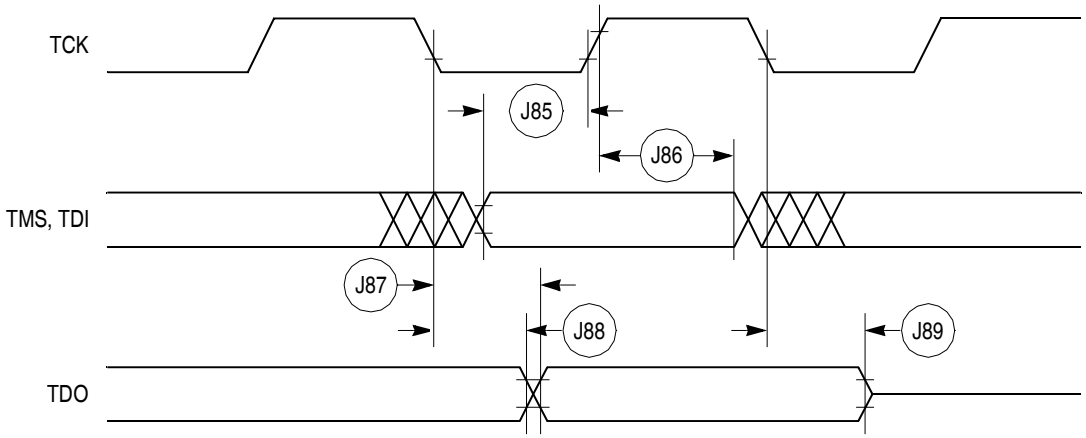

Figure 38. JTAG Test Access Port Timing Diagram

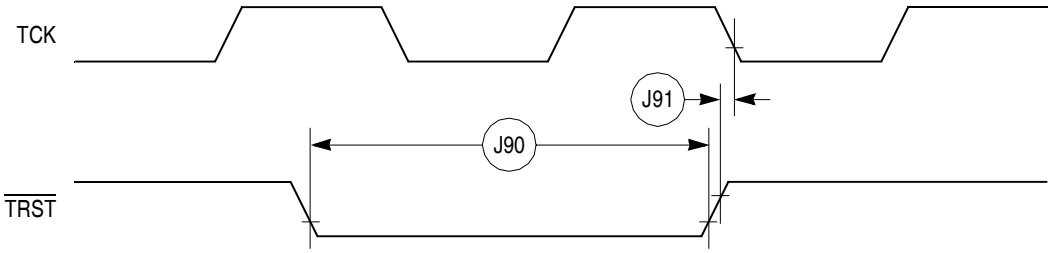

Figure 39. JTAG $\overline{\text{TRST}}$ Timing Diagram

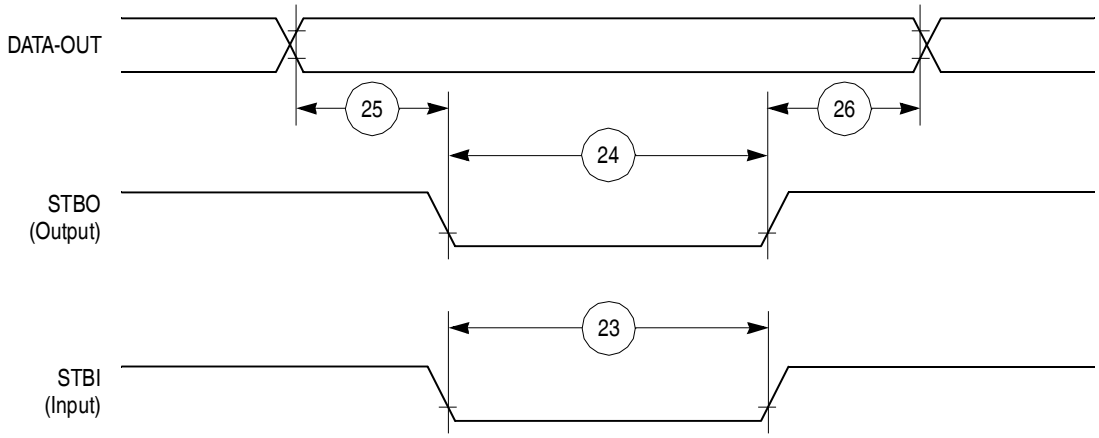

Figure 44. PIP TX (Pulse Mode) Timing Diagram

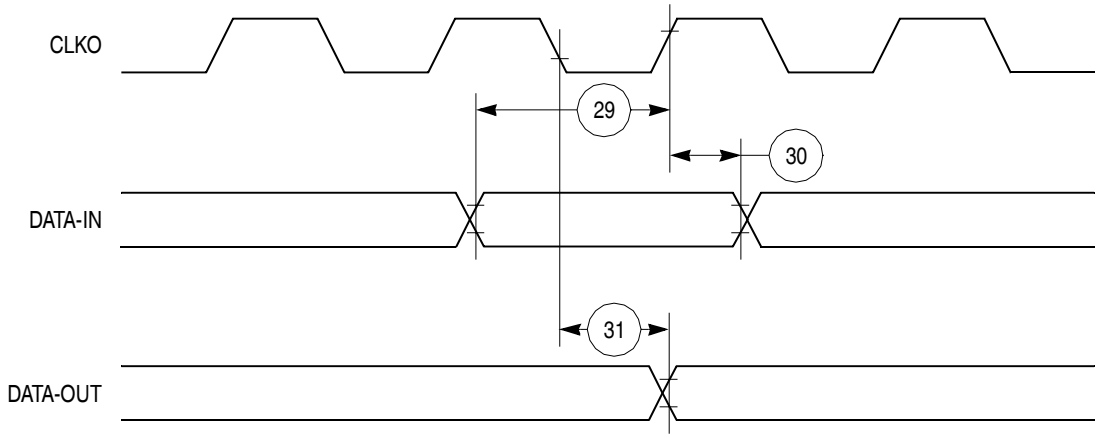

Figure 45. Parallel I/O Data-In/Data-Out Timing Diagram

12.2 Port C Interrupt AC Electrical Specifications

Table 17 shows timings for port C interrupts.

Table 17. Port C Interrupt Timing

Num	Characteristic	33.34 MHz		Unit
		Min	Max	
35	Port C interrupt pulse width low (edge-triggered mode)	55	—	ns
36	Port C interrupt minimum time between active edges	55	—	ns

Figure 46 shows the port C interrupt detection timing.

Table 24. Ethernet Timing (continued)

Num	Characteristic	All Frequencies		Unit
		Min	Max	
134	TENA inactive delay (from TCLK1 rising edge)	10	50	ns
135	$\overline{\text{RSTRT}}$ active delay (from TCLK1 falling edge)	10	50	ns
136	$\overline{\text{RSTRT}}$ inactive delay (from TCLK1 falling edge)	10	50	ns
137	$\overline{\text{REJECT}}$ width low	1	—	CLK
138	CLKO1 low to $\overline{\text{SDACK}}$ asserted [2]	—	20	ns
139	CLKO1 low to $\overline{\text{SDACK}}$ negated [2]	—	20	ns

1 The ratios SyncCLK/RCLK1 and SyncCLK/TCLK1 must be greater or equal to 2/1.

2 $\overline{\text{SDACK}}$ is asserted whenever the SDMA writes the incoming frame DA into memory.

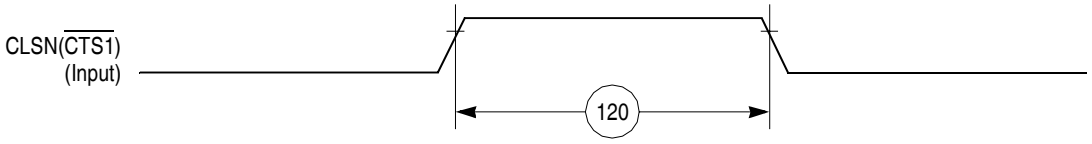

Figure 61. Ethernet Collision Timing Diagram

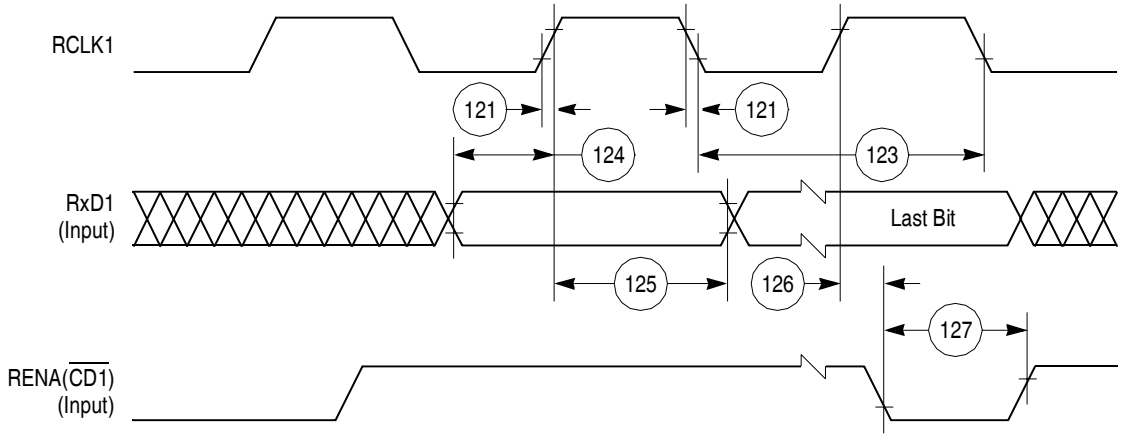

Figure 62. Ethernet Receive Timing Diagram

Table 32. UTOPIA Slave (Split Bus Mode) Electrical Specifications

Num	Signal Characteristic	Direction	Min	Max	Unit
U1	UtpClk rise/fall time (external clock option)	Input	—	4	ns
	Duty cycle		40	60	%
	Frequency		—	33	MHz
U2	UTPB, SOC, Rxclav and Txclav active delay	Output	2	16	ns
U3	UTPB_AUX, SOC_Aux, $\overline{\text{RxEnb}}$, $\overline{\text{TxEnb}}$, RxAddr, and TxAddr setup time	Input	4	—	ns
U4	UTPB_AUX, SOC_Aux, $\overline{\text{RxEnb}}$, $\overline{\text{TxEnb}}$, RxAddr, and TxAddr hold time	Input	1	—	ns

Figure 72 shows signal timings during UTOPIA receive operations.

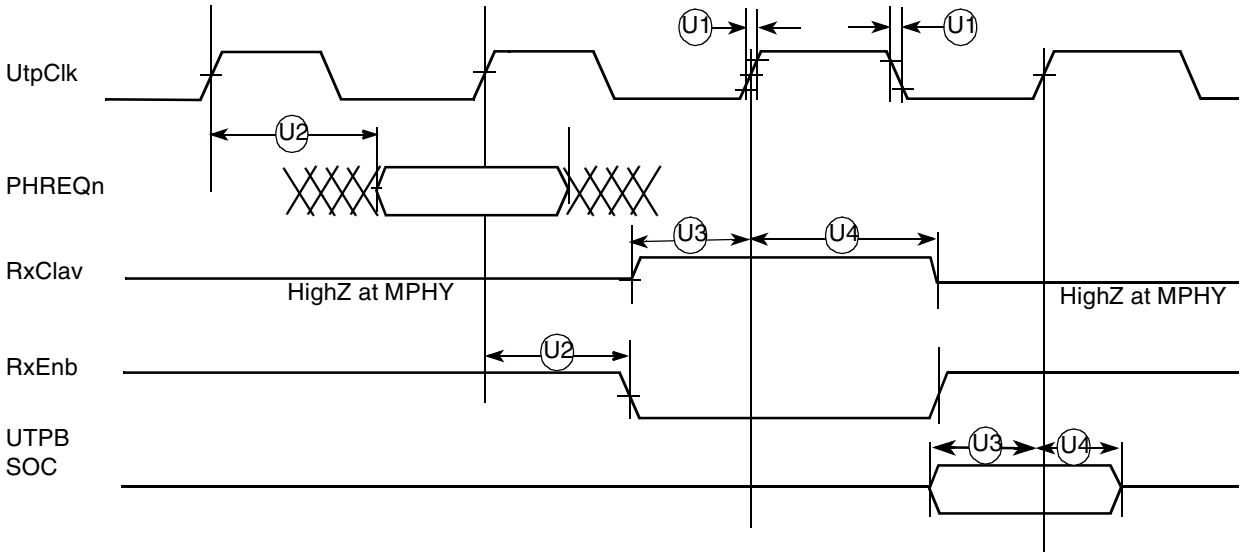

Figure 72. UTOPIA Receive Timing

Figure 73 shows signal timings during UTOPIA transmit operations.

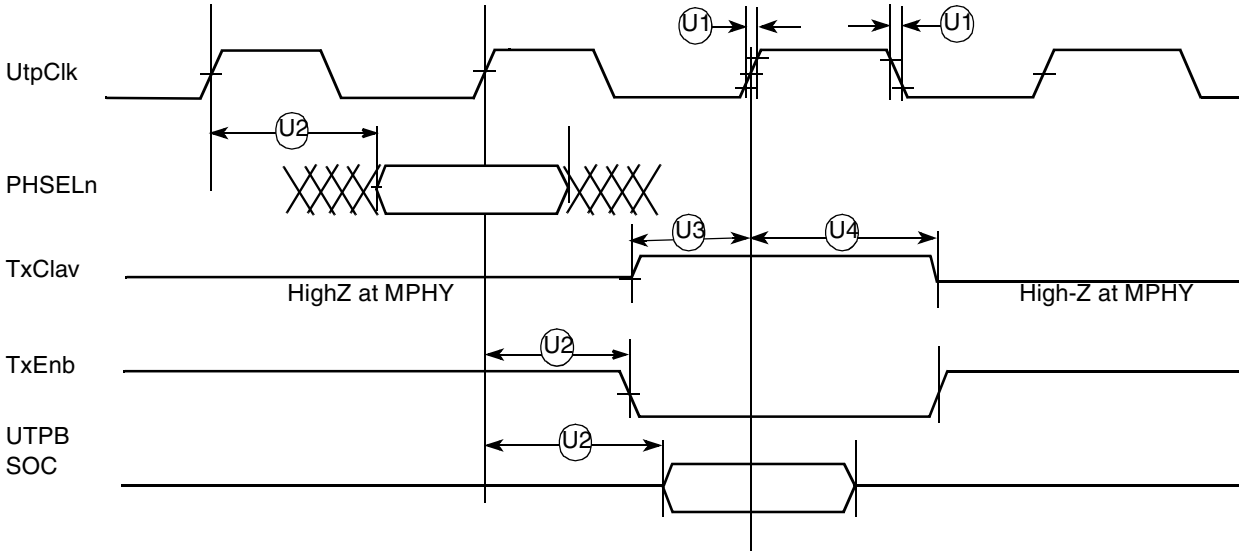

Figure 73. UTOPIA Transmit Timing

14 FEC Electrical Characteristics

This section provides the AC electrical specifications for the fast Ethernet controller (FEC). Note that the timing specifications for the MII signals are independent of system clock frequency (part speed designation). Also, MII signals use TTL signal levels compatible with devices operating at either 5.0 or 3.3 V.

14.1 MII Receive Signal Timing (MII_RXD [3:0], MII_RX_DV, MII_RX_ER, MII_RX_CLK)

The receiver functions correctly up to a MII_RX_CLK maximum frequency of 25 MHz + 1%. There is no minimum frequency requirement. In addition, the processor clock frequency must exceed the MII_RX_CLK frequency – 1%. Table 33 shows the timings for MII receive signal.

Table 33. MII Receive Signal Timing

Num	Characteristic	Min	Max	Unit
M1	MII_RXD[3:0], MII_RX_DV, MII_RX_ER to MII_RX_CLK setup	5	—	ns
M2	MII_RX_CLK to MII_RXD[3:0], MII_RX_DV, MII_RX_ER hold	5	—	ns
M3	MII_RX_CLK pulse width high	35%	65%	MII_RX_CLK period
M4	MII_RX_CLK pulse width low	35%	65%	MII_RX_CLK period

Figure 74 shows the timings for MII receive signal.

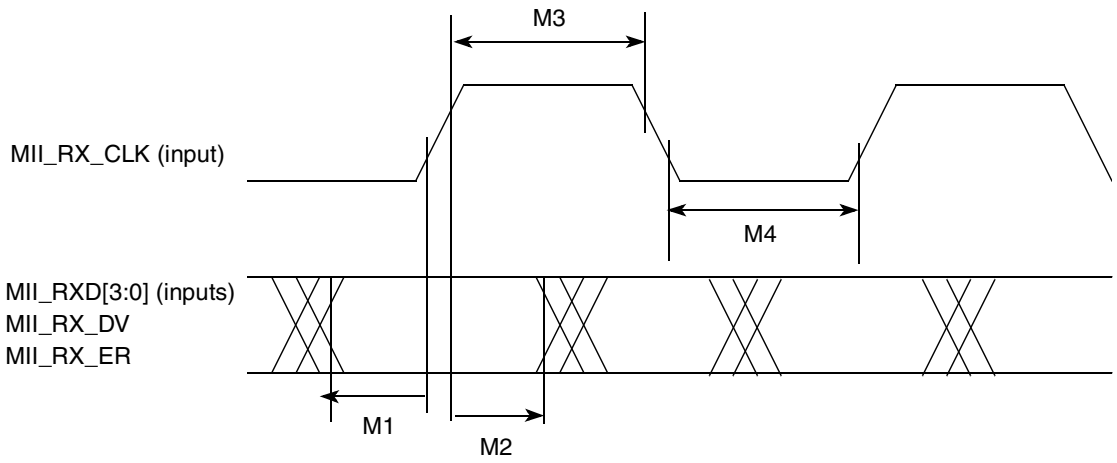

Figure 74. MII Receive Signal Timing Diagram

14.2 MII Transmit Signal Timing (MII_TXD[3:0], MII_TX_EN, MII_TX_ER, MII_TX_CLK)

The transmitter functions correctly up to a MII_TX_CLK maximum frequency of 25 MHz +1%. There is no minimum frequency requirement. In addition, the processor clock frequency must exceed the MII_TX_CLK frequency - 1%.

Table 34 shows information on the MII transmit signal timing.

Table 34. MII Transmit Signal Timing

Num	Characteristic	Min	Max	Unit
M5	MII_TX_CLK to MII_TXD[3:0], MII_TX_EN, MII_TX_ER invalid	5	—	ns
M6	MII_TX_CLK to MII_TXD[3:0], MII_TX_EN, MII_TX_ER valid	—	25	—
M7	MII_TX_CLK pulse width high	35%	65%	MII_TX_CLK period
M8	MII_TX_CLK pulse width low	35%	65%	MII_TX_CLK period

Figure 75 shows the MII transmit signal timing diagram.

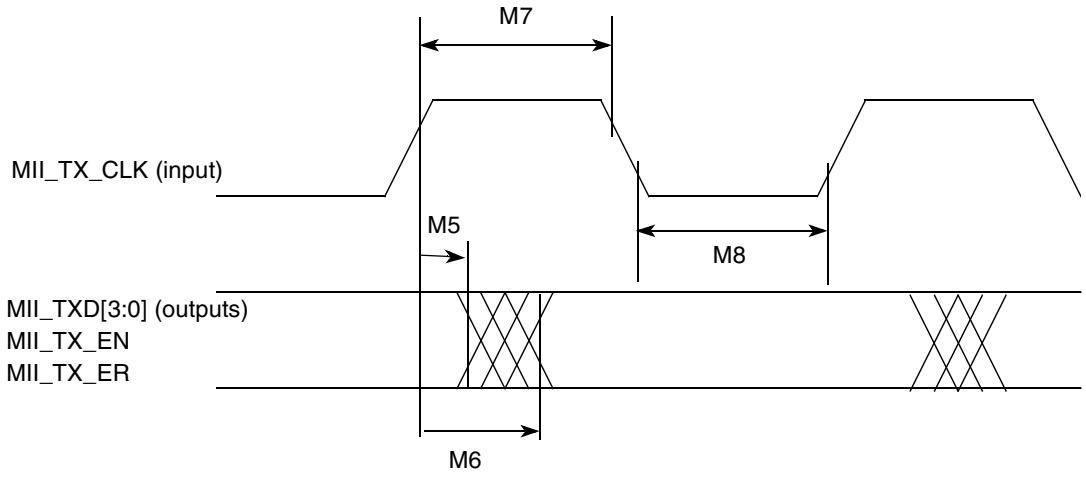

Figure 75. MII Transmit Signal Timing Diagram

14.3 MII Async Inputs Signal Timing (MII_CRS, MII_COL)

Table 35 shows the timing for on the MII async inputs signal.

Table 35. MII Async Inputs Signal Timing

Num	Characteristic	Min	Max	Unit
M9	MII_CRS, MII_COL minimum pulse width	1.5	—	MII_TX_CLK period

Figure 76 shows the MII asynchronous inputs signal timing diagram.

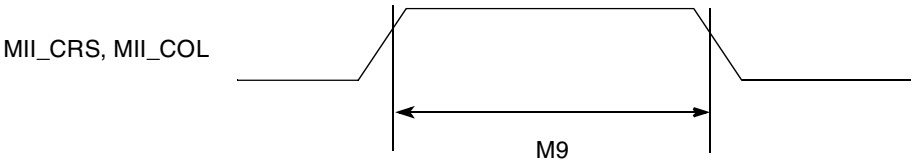

Figure 76. MII Async Inputs Timing Diagram

14.4 MII Serial Management Channel Timing (MII_MDIO, MII_MDC)

Table 36 shows the timing for the MII serial management channel signal. The FEC functions correctly with a maximum MDC frequency in excess of 2.5 MHz. The exact upper bound is under investigation.

Table 36. MII Serial Management Channel Timing

Num	Characteristic	Min	Max	Unit
M10	MII_MDC falling edge to MII_MDIO output invalid (minimum propagation delay)	0	—	ns
M11	MII_MDC falling edge to MII_MDIO output valid (maximum propagation delay)	—	25	ns
M12	MII_MDIO (input) to MII_MDC rising edge setup	10	—	ns

15.1 Pin Assignments

Figure 78 shows the top view pinout of the PBGA package. For additional information, see the *MPC866 PowerQUICC Family User's Manual*.

NOTE: This is the top view of the device.

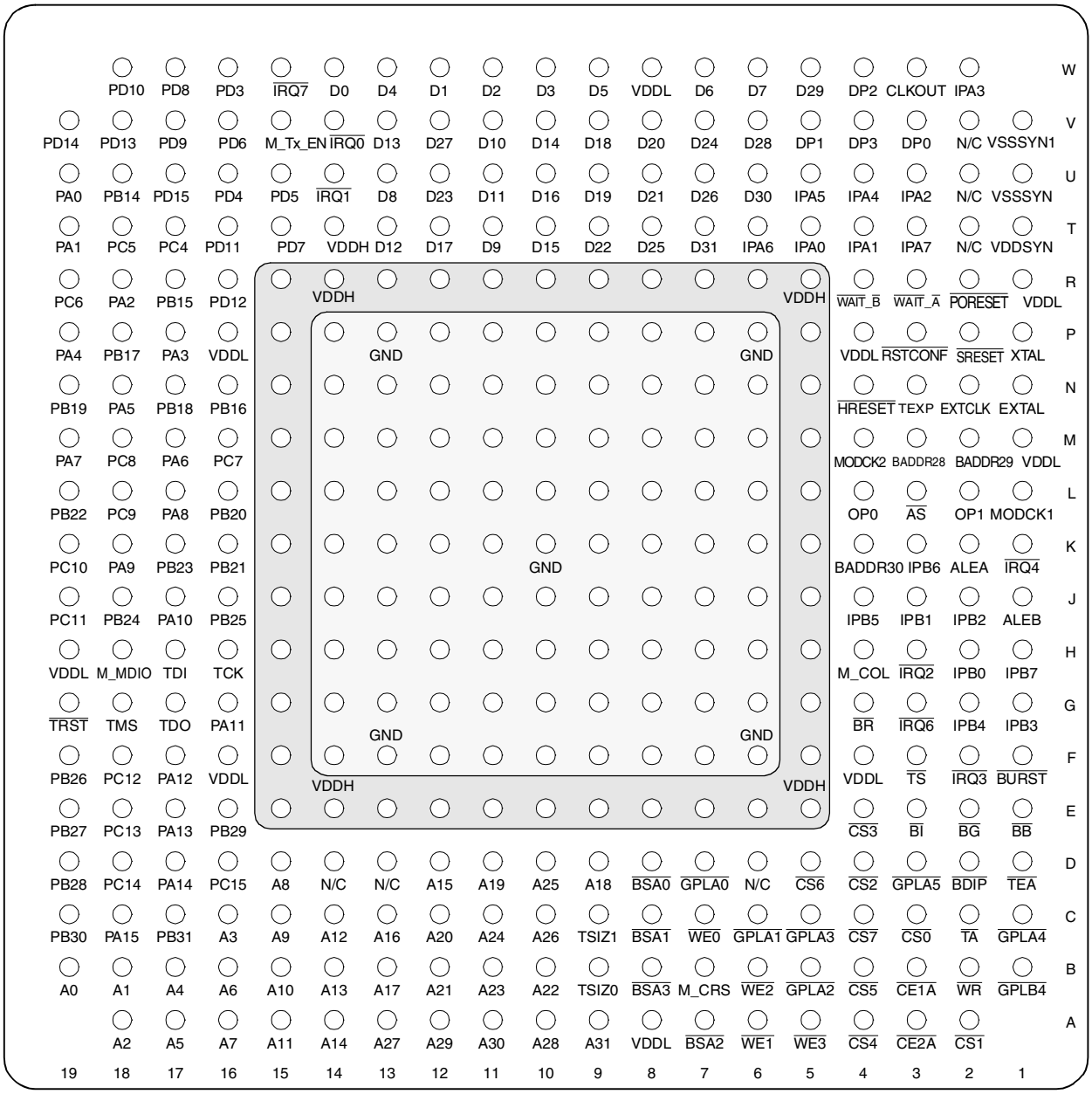

Figure 78. Pinout of the PBGA Package

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